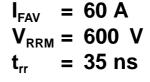
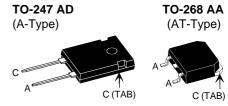


HiPerFRED™ Epitaxial Diode with soft recovery

V _{RSM}	V _{RRM}	Туре	
600	600	DSEP 60-06A	DSEP 60-06AT





A = Anode, C = Cathode, TAB = Cathode

Symbol	Conditions	Maximum Ratings	
I _{FRMS}	$T_{VJ} = T_{VJM}$ $T_{C} = 110$ °C; rectangular, d = 0.5	70 60	A A
I _{FSM}	$T_{VJ} = 45$ °C; $t_p = 10$ ms (50 Hz), sine	600	Α
E _{AS}	$T_{VJ} = 25^{\circ}\text{C}$; non-repetitive $I_{AS} = 1.6 \text{ A}$; L = 180 μH	0.3	mJ
I _{AR}	$V_A = 1.5 \cdot V_R$ typ.; f = 10 kHz; repetitive	0.2	Α
T _{VJ} T _{VJM} T _{stg}		-55+175 175 -55+150	°C °C °C
P _{tot}	T _C = 25°C	230	W
M _d	mounting torque	0.81.2	Nm
Weight	typical	6	g

Symbol	Conditions	Characteristic Values		
		typ.	max.	
I _R ①	$T_{VJ} = 25$ °C $V_R = V_{RRM}$ $T_{VJ} = 150$ °C $V_R = V_{RRM}$		650 2.5	μA mA
V _F ②	$I_F = 60 \text{ A}; \qquad T_{VJ} = 150^{\circ}\text{C}$ $T_{VJ} = 25^{\circ}\text{C}$		1.39 2.04	V
R _{thJC}		0.25	0.65	K/W K/W
t _{rr}	$I_F = 1 \text{ A}$; -di/dt = 300 A/ μ s; $V_R = 30 \text{ V}$; $T_{VJ} = 25^{\circ}\text{C}$			ns
I _{RM}	$V_R = 100 \text{ V}; \ I_F = 130 \text{ A}; -di_F/dt = 100 \text{ A}/\mu\text{s}$ $T_{VJ} = 100 ^{\circ}\text{C}$		8.3	А

Pulse test: ① Pulse Width = 5 ms, Duty Cycle < 2.0 % ② Pulse Width = 300 μ s, Duty Cycle < 2.0 %

Data according to IEC 60747 and per diode unless otherwise specified

IXYS reserves the right to change limits, test conditions and dimensions.

Features

- · International standard package
- · Planar passivated chips
- · Very short recovery time
- Extremely low switching losses
- Low I_{RM}-values
- · Soft recovery behaviour
- Epoxy meets UL 94V-0

Applications

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode in converters and motor control circuits
- Rectifiers in switch mode power supplies (SMPS)
- · Inductive heating
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Advantages

- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{RM} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Dimensions see outlines.pdf

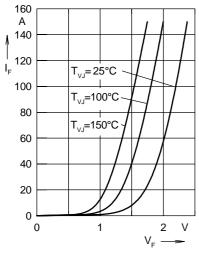


Fig. 1 Forward current I_F versus V_F

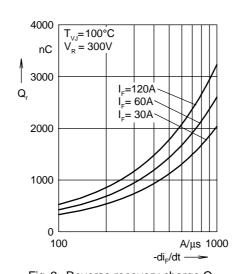
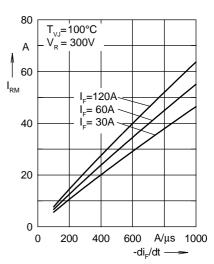


Fig. 2 Reverse recovery charge Q versus -di /dt



 $\begin{array}{ccc} {\rm Fig.\,3} & {\rm Peak\,reverse\,current\,I_{\rm RM}} \\ & {\rm versus\,\, -di_{\rm F}/dt} \end{array}$

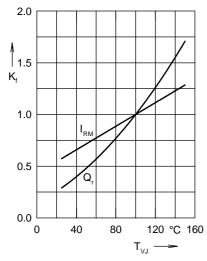


Fig. 4 Dynamic parameters Q_r , I_{RM} versus T_{VJ}

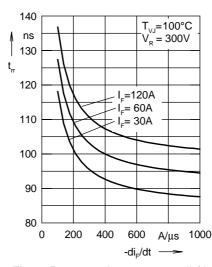


Fig. 5 Recovery time t_{rr} versus $-di_{F}/dt$

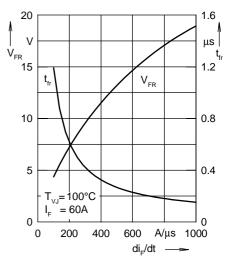


Fig. 6 Peak forward voltage V_{FR} and t_{fr} versus di_{F}/dt

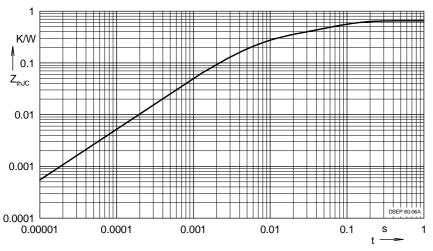


Fig. 7 Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R _{thi} (K/W)	t _i (s)
1	0.324	0.0052
2	0.125	0.0003
3	0.201	0.0385